

Thermally Conductive Gap Filler

Form In Place Gap Filler

LY-TCFIGF

L2Y TCFIGF is a thermally conductive liquid gap filling material. It is a highly conformable, high thermally conductive, and high viscosity type silicone compound.

Special feature

- Thermally conductivity : 1.5, 3.0, 5.5 and 7.0 W/mK
- Excellent thermally conductivity
- Low interfacial resistance
- Low thermal impedance
- Easily form and adheres to moist surface, shapes, and sizes of components.
- Excellent vibration absorption capabilities.

Products supply(Packing method)

-Syringe type, 1Kg Tube, 20Kg Can.

Properties

	TCFIGF-015	TCFIGF-030	TCFIGF-055	TCFIGF-070	Test Method
Appearance (Color)	Paste, Gray	Paste, Pink	Paste, Blue	Paste, Gray	-
Viscosity (23 °C ,1.0(1/s))Pa-s	1,500	3,500	22,000	25,000	ASTM D 1824
Flow Rate (g/min)	22	18.5	19.5	21.0	L2Y Test Method
Weight Loss (wt%)	0.25	0.05	0.06	0.05	ASTM D 412
Specific gravity (23 °C)	2.8	3.2	3.4	3.7	ASTM D 792
Thermal Conductivity (W/mK)	1.5	3.0	5.5	7.0	ASTM D 5470 equivalent
Flame rating	V-0 equivalent				UL-94
Continuous Use Temp.(°C)	-40 ~ +150				